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(54) **DEVICE FOR DETECTING AN ELECTROMAGNETIC RADIATION INCLUDING A THERMAL DETECTOR OVER A READOUT SUBSTRATE AN ACTIVE ELECTRONIC ELEMENT OF WHICH IS LOCATED THE CLOSEST TO THE THERMAL DETECTOR**

(71) Applicant: **COMMISSARIAT A L'ENERGIE ATOMIQUE ET AUX ENERGIES ALTERNATIVES**, Paris (FR)

(72) Inventors: **Sébastien BECKER**, Grenoble Cedex 09 (FR); **Patrick LEDUC**, Grenoble Cedex 09 (FR); **Thomas PERRILLAT-BOTTONET**, Grenoble Cedex 09 (FR)

(73) Assignee: **COMMISSARIAT A L'ENERGIE ATOMIQUE ET AUX ENERGIES ALTERNATIVES**, Paris (FR)

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(57) **ABSTRACT**

The invention relates to a device for detecting an electromagnetic radiation, comprising at least one sensitive pixel including a thermal detector (**10**), and including a readout substrate (**20**) formed of a stack of a readout structure (**23**) and an interconnection structure (**22**). The thermal detector includes a suspended absorbing membrane (**11**), and anchor pillars (**13**). The readout structure (**23**) is located over and in contact with the interconnection structure (**22**); the first active electronic element (**23.1***a*) is directly connected to the upper metallization level; and the anchor pillars (**13**) continuously extend in the readout substrate (**20**) until coming into contact with the upper metallization level.